



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,020mm	3,5	
3	Top Layer	Copper	0,040mm		
4	Dielectric 1	FR-4	1,499mm	4,8	
5	Bottom Layer	Copper	0,040mm		
6	Bottom Solder	Solder Resist	0,020mm	3,5	
7	Bottom Overlay				

PCB NOTES

1. Number of layers - 2
2. Board size - 20.73mm x 25mm. Tolerance - ± 0.1 mm
3. Board thickness - 1.6mm $\pm 10\%$
4. Material - FR-4 High Tg, cooper thickness is 35um (1oz)
5. Solder Mask - Two sides, Green, Liquid. Solder mask mis-registration ± 0.025 mm. No overlap permitted on SMD lands. Solder Mask is in accordance with IPC-SM-840 D, Class H
6. Silkscreen - TOP side only
7. Type of coating - HASL (RoHS)
8. Electrical Test on both sides
9. Min dia of plated hole - 0.3mm
10. Min annular ring - 0.15mm
11. Min trace width - 0.2mm
12. Min clearance - 0.2mm
13. Impedance control - No